

NASA TECH BRIEF

Goddard Space Flight Center

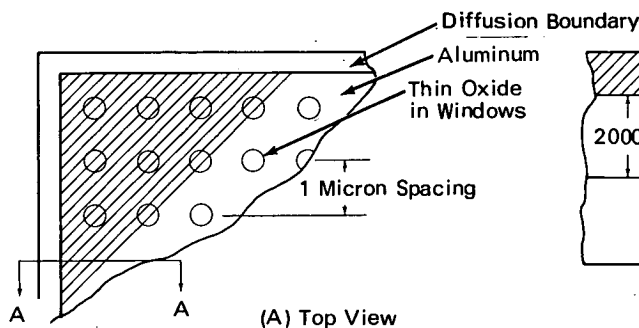


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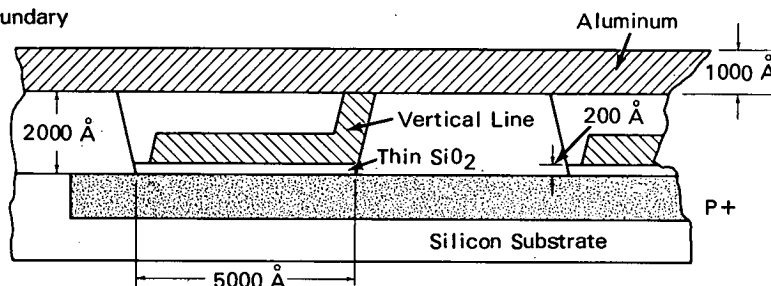
Nonvolatile Read/Write Memory Element: A Concept

A nonvolatile read/write memory with a limited number of programming cycles may be achieved through the use of verticle, fusible links in series with oxide-breakthrough elements. The memory

of the oxide windows. An extremely thin aluminum layer is needed in order to obtain the high current density required for fusing at low input-power levels.



(A) Top View



(B) Expanded Cross-Section A-A

elements can be fabricated with integrated circuit technology and are ideal for low-power digital computer applications.

A cross-section view of a representative element (see fig.) shows the fusible link, which consists of a thin aluminum film evaporated on a silicon dioxide layer, and the oxide breakthrough element. Initially, the memory element is an open circuit. If a high voltage pulse is applied, the oxide breakthrough element changes into a conductive path and the element appears to have low resistance. A subsequent high current pulse will open the fusible link, and the memory element again appears to have a high resistance. The high and low resistance values determine the appropriate logic state.

The fabrication process consists of etching small windows, one to five micrometers in diam., in a thick oxide. An oxide approximately 200 Å is grown or deposited for the breakthrough device. A thin aluminum layer is then deposited over all

In operation, each memory element is programmed to be either an open circuit (OC) or a short circuit (SC). The initial OC state is achieved by opening the fuse with a large current; the SC state is achieved by breaking down the oxide with a large voltage. These operations limit the number of times that the memory can be programmed. However, since the element density exceeds 2×10^6 elements per cm^2 , a sufficient number of elements are available for reprogramming; e.g., in a 256 bit memory array occupying an area of 100×100 mils, nearly 100 memory element pairs per bit can be obtained. This means that the memory could be reprogrammed 100 times. If a larger number of bits is required, such as 1024 bits, then the memory could be programmed more than 25 times.

Notes:

1. Related work on low current fusible links and oxide breakthrough structures is reported in

(continued overleaf)

NASA CR-106493 (N69-41187), "Read Only Memories," available through the National Technical Information Service, Springfield, Virginia 22151.

2. Requests for further information may be directed to:

Technology Utilization Officer
Goddard Space Flight Center
Greenbelt, Maryland 20771
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No patent action is contemplated by NASA.

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